

- Small plastic SMD package
- Switching speed: max. 50 ns
- General application
- Continuous reverse voltage: max. 200 V
- Repetitive peak reverse voltage: max. 250 V
- Repetitive peak forward current: max. 625 mA.

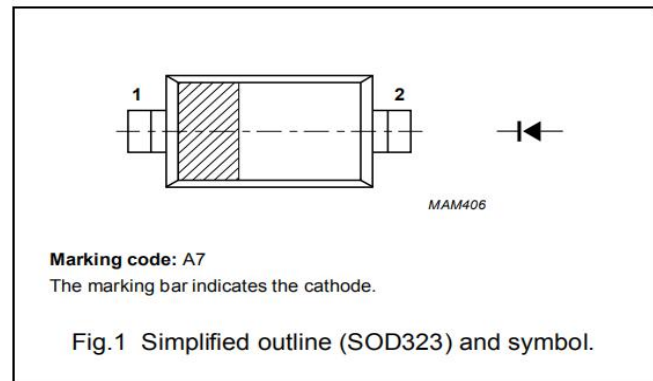
APPLICATIONS

- General purpose switching in e.g. surface mounted circuits.

DESCRIPTION

The BAS321 is a general purpose diode fabricated in planar technology and encapsulated in a plastic SOD323 package.

PIN	DESCRIPTION
1	cathode
2	anode



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BAS321	-	plastic surface mounted package; 2 leads	SOD323

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		-	250	V
V_R	continuous reverse voltage		-	200	V
I_F	continuous forward current	see Fig.2; note 1	-	250	mA
I_{FRM}	repetitive peak forward current	$t_p < 0.5$ ms; $\delta \leq 0.25$	-	625	mA
I_{FSM}	non-repetitive peak forward current	square wave; $T_j = 25$ °C prior to surge; see Fig.4			
		$t = 1$ ∞ s	-	9	A
		$t = 100$ ∞ s	-	3	A
		$t = 10$ ms	-	1.7	A
P_{tot}	total power dissipation	$T_{amb} = 25$ °C; note 1	-	300	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-	150	°C

Note

1. Device mounted on an FR4 printed circuit-board.

CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V_F	forward voltage	see Fig.3		
		$I_F = 100\text{ mA}$	1	V
		$I_F = 200\text{ mA}$	1.25	V
I_R	reverse current	see Fig.5		
		$V_R = 200\text{ V}$	100	nA
		$V_R = 200\text{ V}; T_j = 150\text{ }^\circ\text{C}$	100	μA
C_d	diode capacitance	$f = 1\text{ MHz}; V_R = 0$; see Fig.6	2	pF
t_{rr}	reverse recovery time	when switched from $I_F = 30\text{ mA}$ to $I_R = 30\text{ mA}; R_L = 100\ \Omega$; measured at $I_R = 3\text{ mA}$; see Fig.8	50	ns

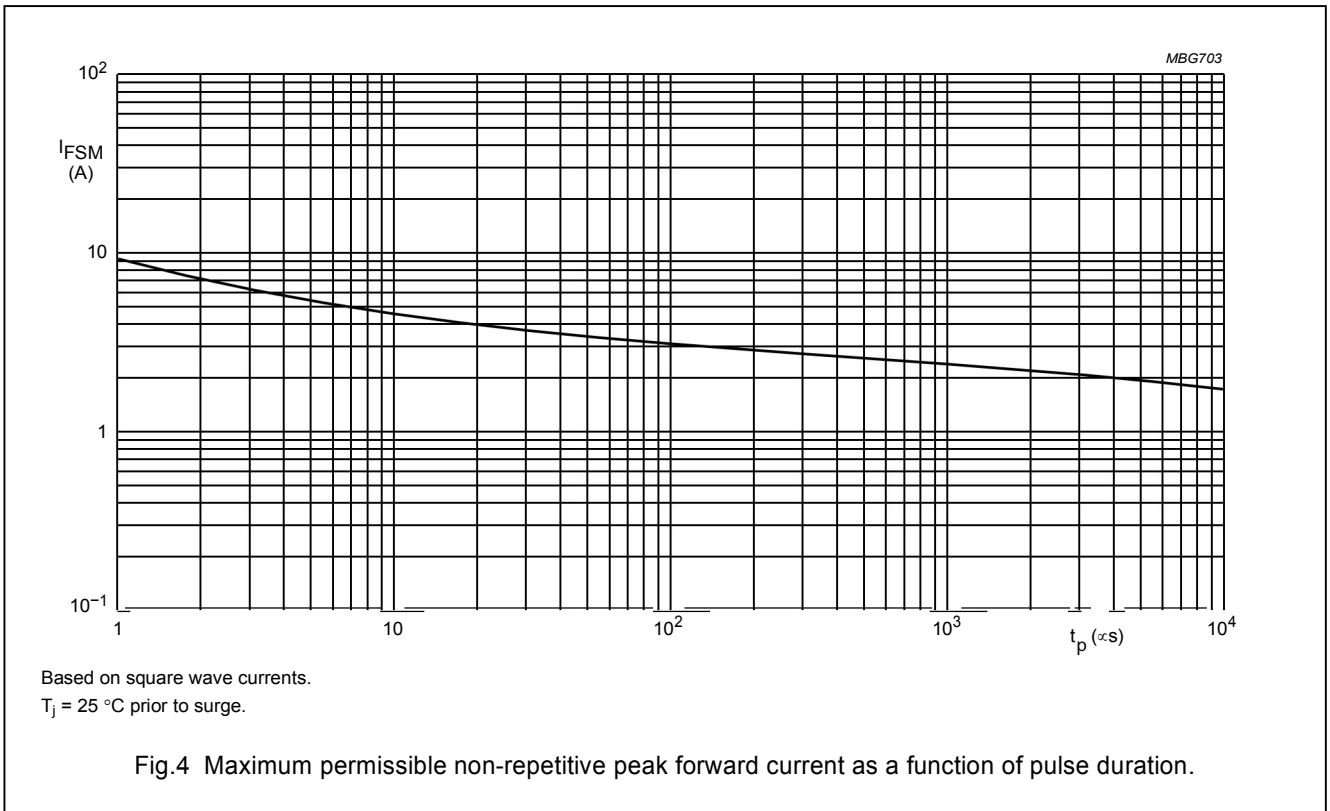
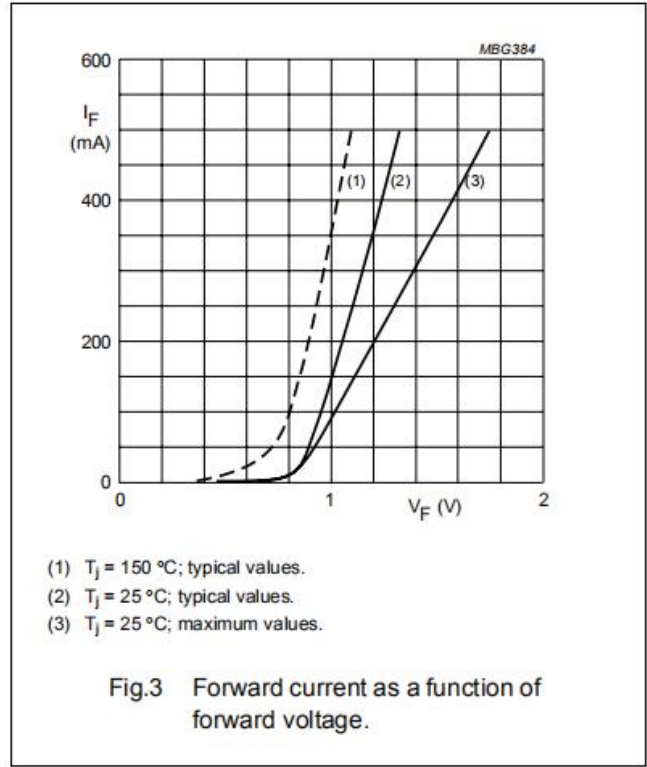
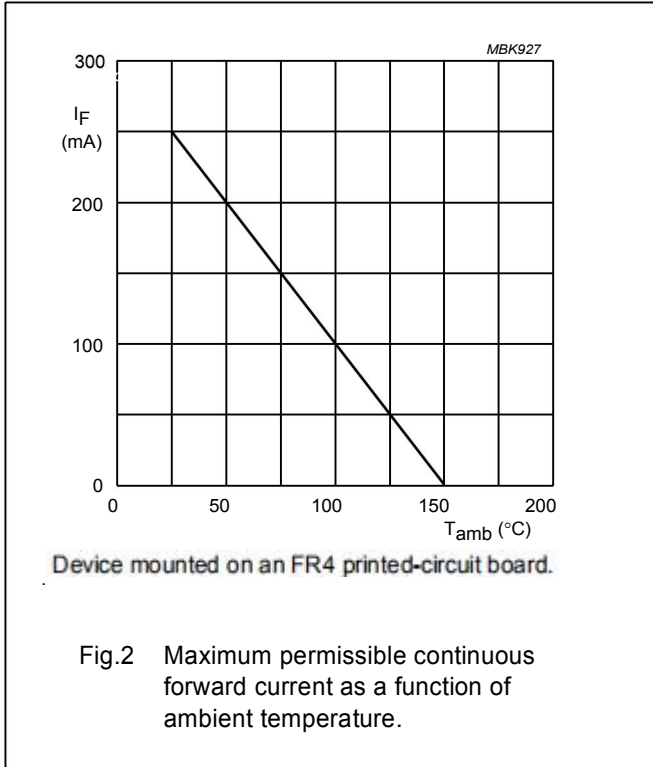
THERMAL CHARACTERISTICS

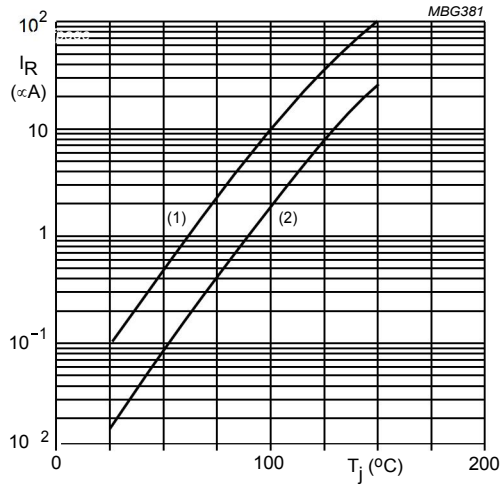
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-s)}$	thermal resistance from junction to soldering point	$T_s = 90\text{ }^\circ\text{C}$; note 1	130	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 2	366	K/W

Notes

1. Soldering point of cathode tab.
2. Device mounted on an FR4 printed circuit board.

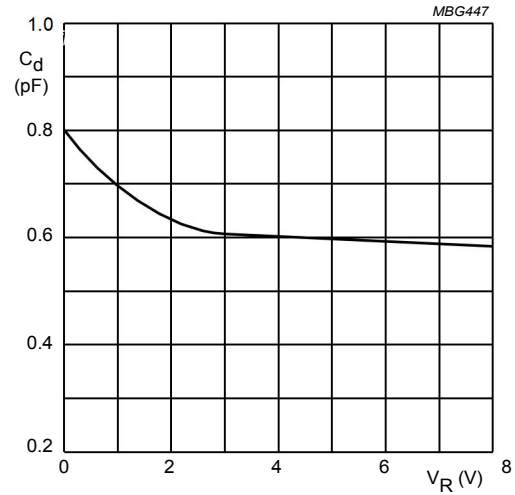
GRAPHICAL DATA





- (1) $V_R = V_{Rmax}$; maximum values.
 (2) $V_R = V_{Rmax}$; typical values.

Fig.5 Reverse current as a function of junction temperature.



$f = 1$ MHz; $T_j = 25$ °C.

Fig.6 Diode capacitance as a function of reverse voltage; typical values.

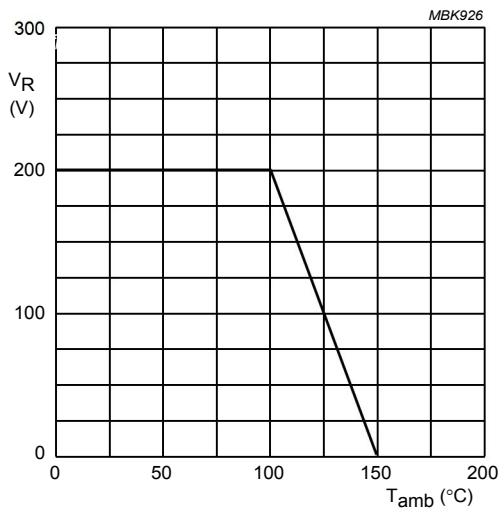
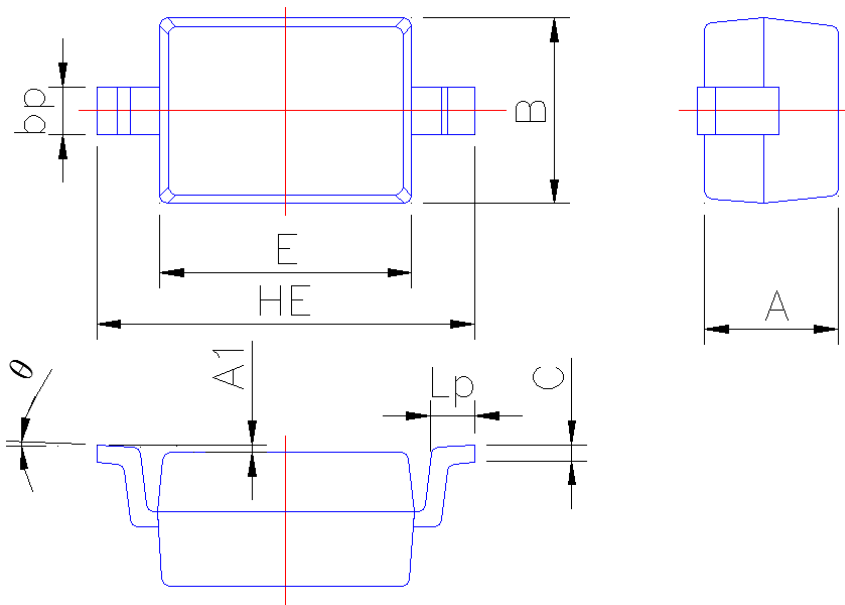


Fig.7 Maximum permissible continuous reverse voltage as a function of the ambient temperature.

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323



Symbol	Dimension in Millimeters	
	Min	Max
A	0.95	1.15
A1	0.010	0.100
B	1.20	1.40
bp	0.25	0.40
C	0.09	0.150
E	1.60	1.80
HE	2.30	2.70
Lp	0.20	0.40
θ	0°	5°